

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (previously presented) A slurry for chemical mechanical polishing, which comprises a silica polishing material, an oxidizing agent, a benzotriazole-based compound, a diketone and water, and

wherein said diketone is at least one type of a compound selected from the group consisting of 1, 2-diketones, 1, 3-diketones and 1, 4-diketones, and

wherein a content weight ratio of said diketone to said benzotriazole-based compound (diketone/benzotriazole-based compound) is not less than 0.05 but not greater than 50.

2-3. (cancelled)

4. (original) A slurry for chemical mechanical polishing according to Claim 1, wherein a value of a pH is in a range of 1 to 7.

5. (original) A slurry for chemical mechanical polishing according to Claim 1, wherein said silica polishing material is colloidal silica.

6. (currently amended) The slurry for chemical mechanical polishing according to claim 1, wherein a content weight ratio of said diketone to said benzotriazole-based

compound (diketone/benzotriazole-based compound) is not less than ~~0.05~~ 0.1 but not greater than ~~50~~ 10.

7. (new) The slurry for chemical mechanical polishing according to claim 1, wherein the content of the silica polishing material is not less than 1 wt%.

8. (new) The slurry for chemical mechanical polishing according to claim 1, wherein the content of the silica polishing material is not less than 1 wt% but not greater than 10 wt%.

9. (new) The slurry for chemical mechanical polishing according to claim 1, wherein the content of the benzotriazole-based compound is not less than 0.001 wt% but not greater than 0.5 wt%.

10. (new) The slurry for chemical mechanical polishing according to claim 1, wherein the content of the diketone is not less than 0.001 wt% but not greater than 5 wt%.